PIN'S NUMBER

10.3

7.6
7.4

C △5 △9 B

1

PIN 1 INDEX

54

△4 △9 18.0
17.8

B ← → B

27

28

5.15

2X 27 TIPS
⌒ 0.3 A B C

△7

2.65
2.35

52X
0.65

A
SEATING PLANE

54X
⌒ 0.1 A

A ← → A

A ← → A

PLATING METAL

(0.29)

0.30
0.25

(0.25)

BASE METAL

0.38
0.22

⊕ 0.13 Ⓜ A B C

△6

SECTION A-A △8

MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE:
54LD SOIC W/B, 0.65 PITCH
CASE-OUTLINE

DOCUMENT NO: 98ASA99294D   REV: C

STANDARD: NON-JEDEC

SOT1764-1   30 MAR 2016

0° MIN

R0.08 MIN

0.25
GAUGE PLANE

0.29
0.13

0.9
0.5

8°
0°

SECTION B-B

MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE

TITLE: 54LD SOIC W/B, 0.65 PITCH CASE-OUTLINE	DOCUMENT NO: 98ASA99294D REV: C
	STANDARD: NON-JEDEC
	SOT1764-1 30 MAR 2016

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M−1994.

3. DATUMS B AND C TO BE DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS
    EXIT THE PLASTIC BODY.

⚠4. THIS DIMENSION DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS. MOLD
    FLASH, PROTRUSION OR GATE BURRS SHALL NOT EXCEED 0.15 MM PER SIDE. THIS
    DIMENSION IS DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT
    THE PLASTIC BODY.

⚠5. THIS DIMENSION DOES NOT INCLUDE INTER−LEAD FLASH OR PROTRUSIONS. INTER−LEAD
    FLASH AND PROTRUSIONS SHALL NOT EXCEED 0.25 MM PER SIDE. THIS DIMENSION IS
    DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.

⚠6. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION
    SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.46 mm. DAMBAR CANNOT BE LOCATED ON
    THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT
    LEAD SHALL NOT BE LESS THAN 0.07 mm.

⚠7. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

⚠8. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.1 mm AND
    0.3 mm FROM THE LEAD TIP.

⚠9. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM. THIS DIMENSION IS
    DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD
    FLASH, TIE BAR BURRS, GATE BURRS AND INTER−LEAD FLASH, BUT INCLUDING ANY
    MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.

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TITLE: 54LD SOIC W/B, 0.65 PITCH, CASE OUTLINE	DOCUMENT NO: 98ASA99294D	REV: C
	STANDARD: NON−JEDEC	
	SOT1764−1	30 MAR 2016